# Specification of Thermoelectric Module TETC1-04611T200

## **Description**

The 46 couples, 6 mm  $\times$  60/64 mm size single module is made of selected high performance ingot and fabricated by our unique "soft" processes to achieve superior cooling/heating performance. The module is able to run over one hundred thousand thermal cycles in 70  $\,^{\circ}$ C temperature change range with less 3% degrading. All the dices and metallic parts are coated with a layer of thin film for anti-corrosion and oxidation in high temperature that ensure the module can work in high temperature for long life. It is good for the need of frequently cooling down and heating up to 200  $\,^{\circ}$ C applications. We can design and manufacture the custom made module according to your special requirements.

#### **Features**

- High effective cooling and efficiency.
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

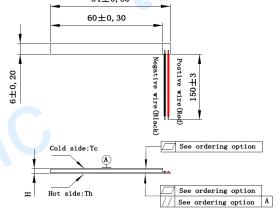
# **Application**

- Food and beverage service refrigerator
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling
- CPU cooler and scientific instrument
- Photonic and medical systems

### **Performance Specification Sheet**

Th(°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>		
DT <sub>max</sub> (℃)	74	83	Temperature Difference between cold and hot side of the module		
			when cooling capacity is zero at cold side		
U <sub>max</sub> (Voltage)	5.9	6.4	Voltage applied to the module at DT <sub>max</sub>		
I <sub>max(</sub> amps)	10.8	10.8	DC current through the modules at DT <sub>max</sub>		
Q <sub>Cmax</sub> (Watts)	41.7	44.9	Cooling capacity at cold side of the module under DT=0 °C		
AC resistance(ohms)	0.41	0.44	The module resistance is tested under AC		
Tolerance (%)	±10		For thermal and electricity parameters		

# Geometric Characteristics Dimensions in millimeters



# **Manufacturing Options**

#### A. Solder:

1.T200: CuSn (Melting Point=227 °C)

#### **B. Sealant:**

1. SS: Silicone sealing

#### C. Ceramics:

1. Alumina (Al2O3, white 96%)

#### **D. Ceramics Surface Options:**

1.Blank ceramics (not metalized)

#### Flatness/ Parallelism Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 2.95±0.15	0:0.10/0.10	150±3/Specify

# **Operation Cautions**

- Cold side of the module sticked on the object being cooled
- Hot side of the module mounted on a heat radiator
- Work under DC

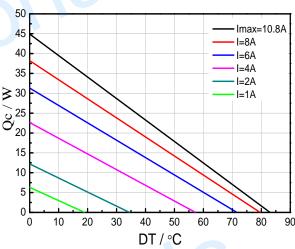
- $\bullet$  Operation below  $I_{\text{max}}$  or  $V_{\text{max}}$
- Operation or storage module below 100 °C

#### **Performance Curve**

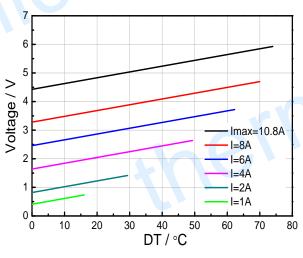


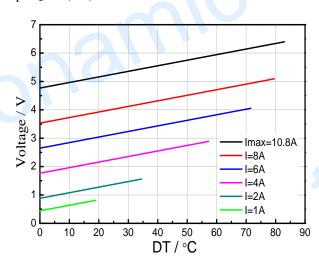
#### 45 Imax=10.8A 40 I=8A I=6A 35 I=4A 30 I=2A I=1A ≥<sup>25</sup> ွဲ20 တ 15 10 5 20 DT / °C 70 80

#### Performance Curves at Th=50 ℃

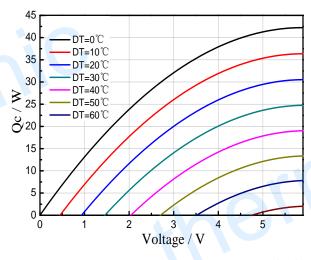


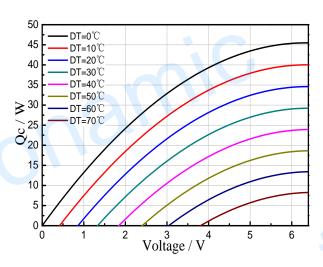
Standard Performance Graph Qc= f(DT)



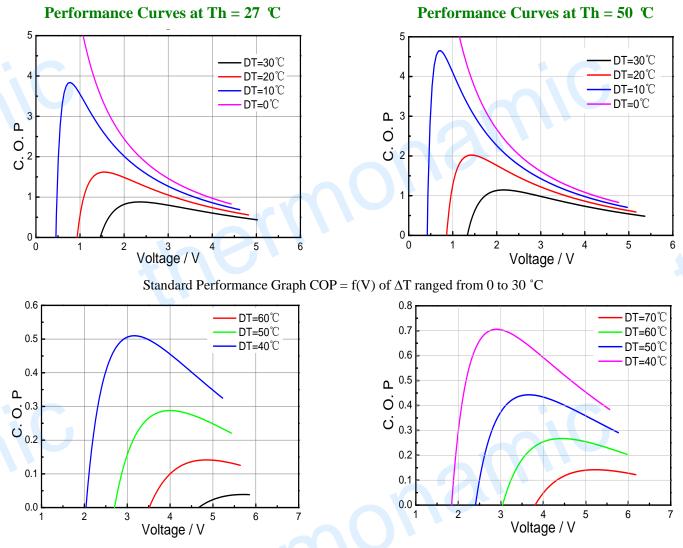


Standard Performance Graph  $V = f(\Delta T)$ 





Standard Performance Graph Qc = f(V)

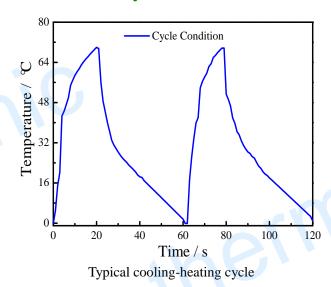


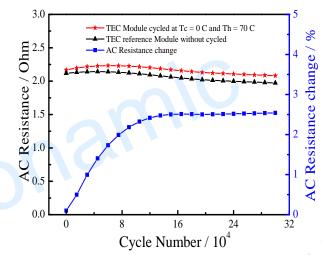
Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 40 to 60/70 °C

**Remark:** The coefficient of performance (COP) is the cooling power Qc/Input power (V  $\times$ I).

A typical 127 couples module is fabricated by the unique "soft" process and has demonstrated that it only has 2.5% degrading after 300,000 thermal cycling. The below graphic shows that in beginning 120,000 cycles, it degrade about 2.5%, and then go on stable with very tiny degrading in further 180,000 thermal cycles. It is derived out that the modules can go over million thermal cycles.

# **TETC Thermal Cycle Lifetime Test**





The Chart for AC Resistance and AC Resistance Changes vs. Cycle Number